

# P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
- 60	0.019 at V <sub>GS</sub> = - 10 V	- 53	38 nC			
- 60	0.026 at V <sub>GS</sub> = - 4.5 V	- 42	30 110			

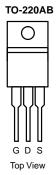
#### **FEATURES**

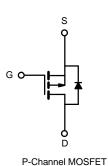
- TrenchFET® Power MOSFET
- 100 % UIS Tested

## **APPLICATIONS**

Load Switch







Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 60	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20			
	T <sub>C</sub> = 25 °C		- 53 <sup>a</sup>		
Continuous Proin Current (T. 450 °C)	T <sub>C</sub> = 70 °C		- 46.8		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	-9.2 <sup>b</sup>	$\exists$	
	T <sub>A</sub> = 70 °C		- 8.1 <sup>b</sup>	A	
Pulsed Drain Current	I <sub>DM</sub>	- 200			
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	- 45		
Single Pulse Avalanche Energy	L = U.1 IIII	E <sub>AS</sub>	101	mJ	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		69 <sup>a</sup>	۸	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.1 <sup>b</sup>	A	
	T <sub>C</sub> = 25 °C		104.2 <sup>a</sup>		
Mantagan Barras Black of a	T <sub>C</sub> = 70 °C	Б	66.7 <sup>a</sup>		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.1 <sup>b</sup>	W	
	T <sub>A</sub> = 70 °C		2 <sup>b</sup>		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	$R_{thJA}$	33	40	°C/W	
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.98	1.2	30/00	

#### Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 60			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J I <sub>D</sub> = - 250 μA		68		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 <sub>D</sub> = - 230 μΑ		- 5.2		11107 C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	,	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			Α	
	В	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.019			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.026		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 50 A	20			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			3500		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		390			
Reverse Transfer Capacitance	C <sub>rss</sub>			290			
Total Cata Chausa	Qg	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 55 A	76		115		
Total Gate Charge				38	60	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -55 \text{ A}$		16			
Gate-Drain Charge	$Q_{gd}$			19			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		5.2		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	$V_{DD} = -2 \text{ V}, R_L = 2 \Omega$		7	15	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		70	110		
Fall Time	t <sub>f</sub>			40	60		
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 69		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 150	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 30 A		- 1	- 1.5	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			45	68	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			59	120	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -50 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		29			
Reverse Recovery Rise Time	t <sub>b</sub>			16		ns	

#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

I<sub>D</sub> - Drain Current (A)

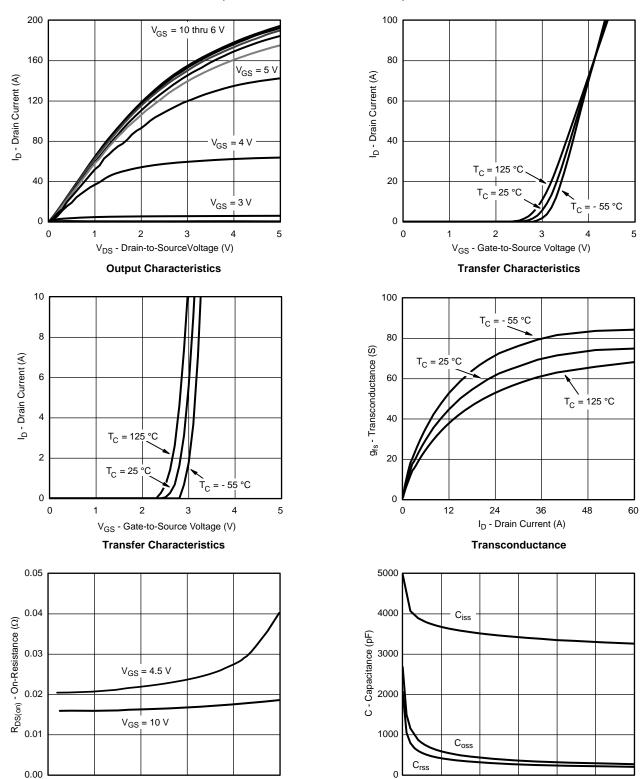
On-Resistance vs. Drain Current

Capacitance

V<sub>DS</sub> - Drain-to-Source Voltage (V)

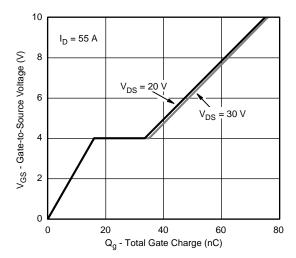


### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

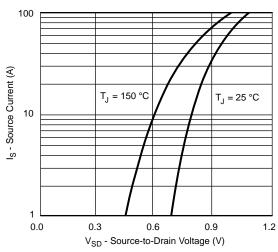




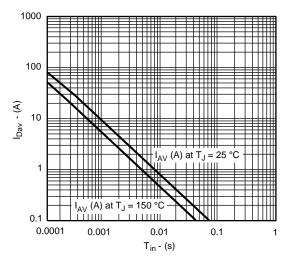
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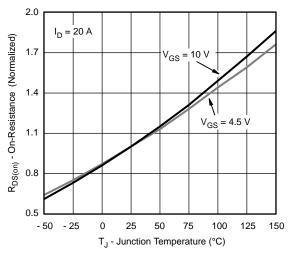
#### **Gate Charge**



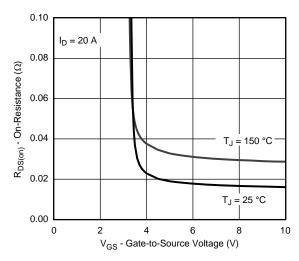
Source-Drain Diode Forward Voltage



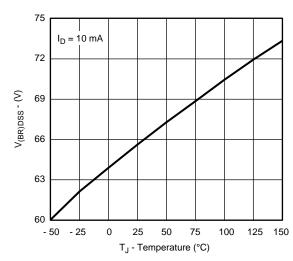
Single Pulse Avalanche Current Capability vs. Time



On-Resistance vs. Gate-to-Source Voltage



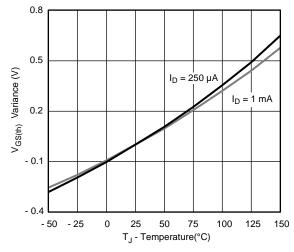
On-Resistance vs. Gate-to-Source Voltage

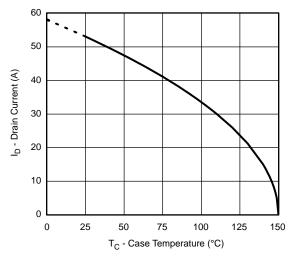


Drain-Source Breakdown Voltage vs. Junction Temperature

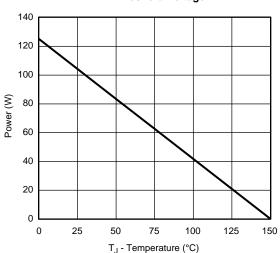


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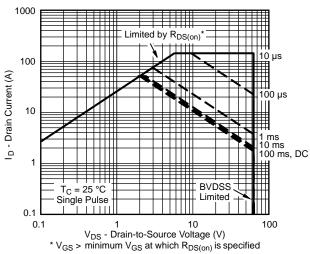




#### Threshold Voltage

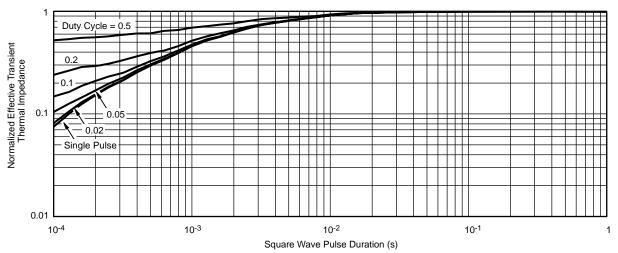


Max. Drain Current vs. Case Temperature



#### Power Derating, Junction-to-Case



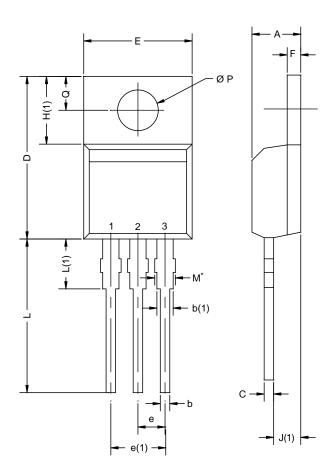


Normalized Thermal Transient Impedance, Junction-to-Case

5



## **TO-220AB**



	MILLIM	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

#### Notes

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM

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